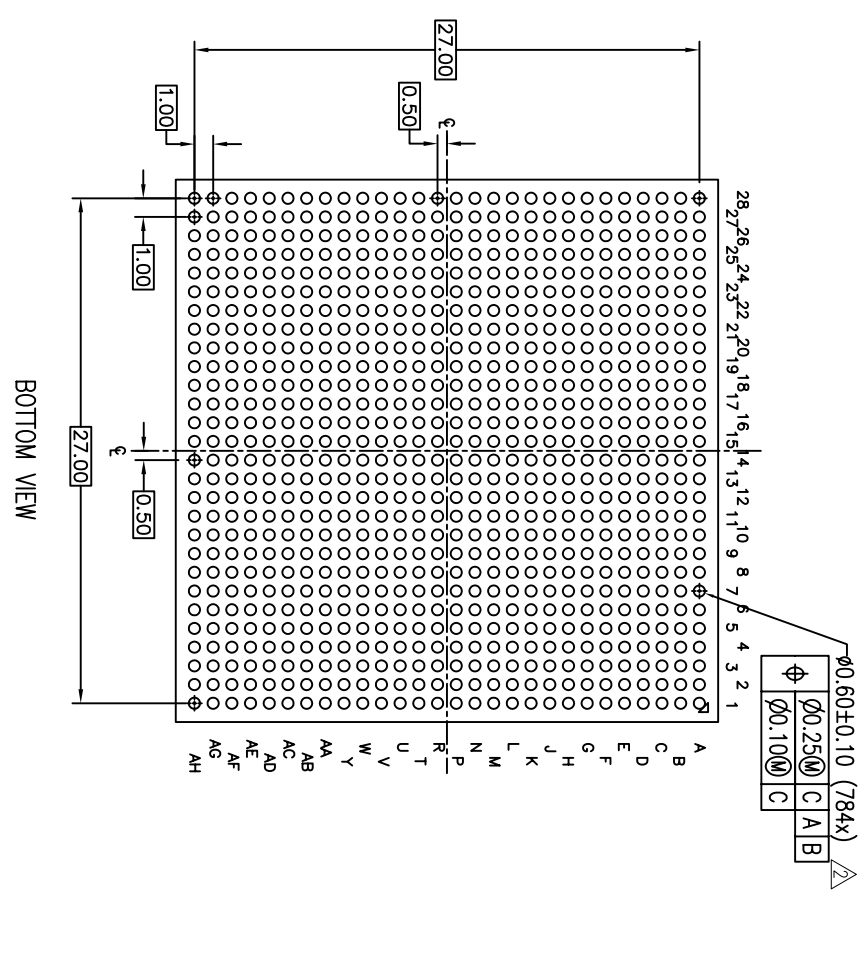
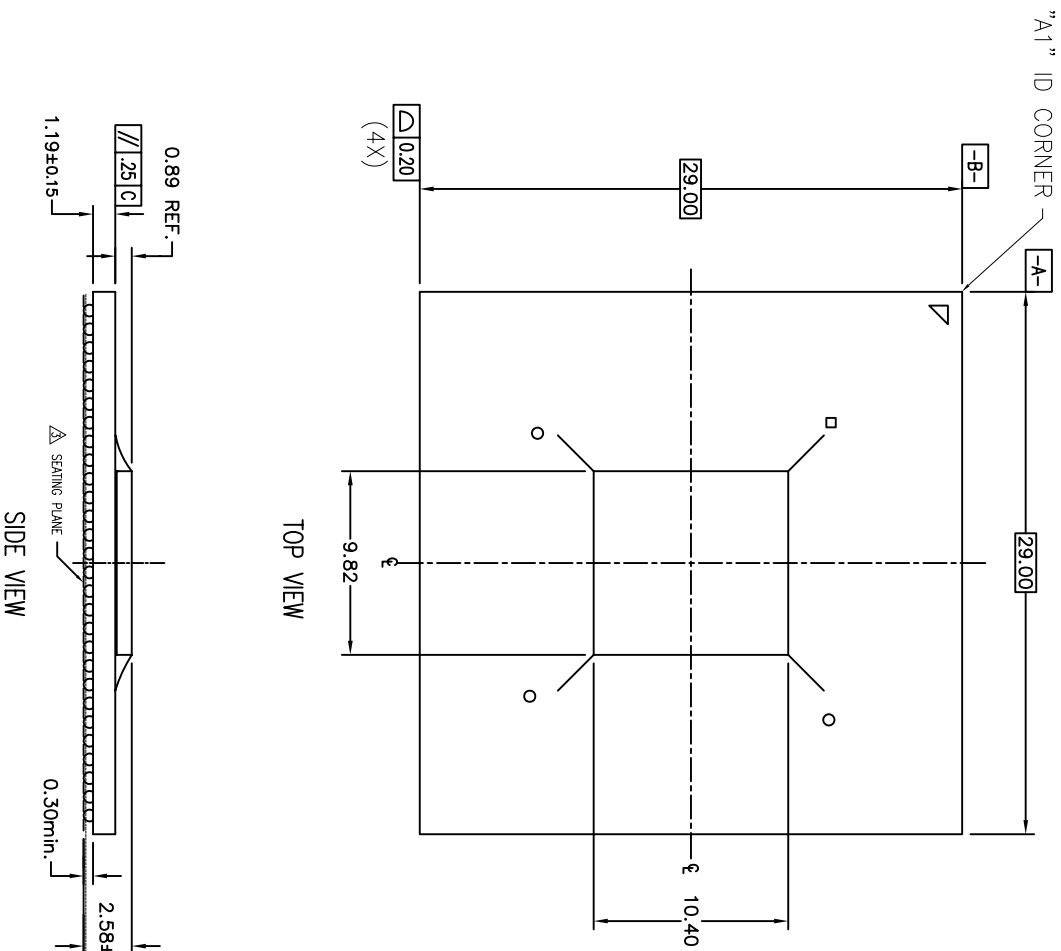


NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1994 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM -C-
- 2 SEATING PLANE AND PRIMARY DATUM -C- ARE DEFINED BY THE CONTACT POINTS OF THREE OR MORE SOLDER BALLS THAT SUPPORT THE DEVICE WHEN PLACED ON A TOP OF A PLANAR SURFACE.
- 4 ALL DIMENSIONS ARE IN MILLIMETERS



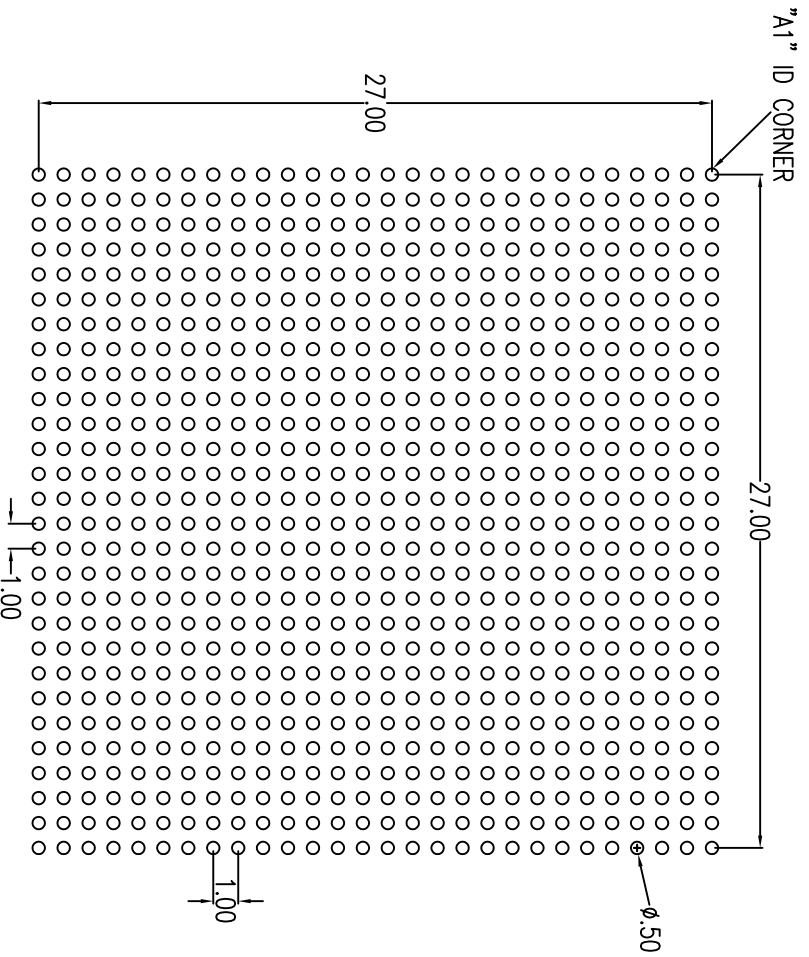
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	06/02/10	K. STAHN
01	PACKAGE THICKNESS UPDATED	06/15/10	K. STAHN
02	DIMENSIONS ADDED AND FORMAT UPDATED	10/06/10	M.ROY
03	COMBINE PCD & LAND PATTERN	06/03/13	K. STAHN

TOLERANCES UNLESS SPECIFIED	
DECIMAL	±
ANGULAR	±
XXX.X	0.05
XXXX	±
XXXXX	±
APPROVALS	DATE
DRAWN: PSC/DP	07/08/09
CHECKED	
SIZE	DRAWING NO.
C	PSC-4277
DO NOT SCALE DRAWING	SHEET 1 OF 2

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 FAX: (408) 284-3572
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TITLE: HM/RM 784 PACKAGE OUTLINE
 FCBG4 29.0 x 29.0mm, 1.0mm pitch
 -Die Size: 9.82mm x 10.4mm-

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	06/02/10	K. STAHN
01	PACKAGE THICKNESS UPDATED	06/15/10	K. STAHN
02	DIMENSIONS ADDED AND FORMAT UPDATED	10/06/10	M.ROY
03	COMBINE POD & LAND PATTERN	06/03/13	K. STAHN



RECOMMENDED LAND PATTERN DIMENSION (mm)

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		DATE	
DECIMAL	ANGULAR	07/08/09	
XXX±	±		
XXXX			
XXXX±			
APPROVALS		TITLE	
DRAWN	DATE	HW/RM 784 PACKAGE OUTLINE	
09/02/09		FCBGA 29.0 x 29.0mm, 1.0mm pitch	
CHECKED		Die Size: 9.82mm x 10.4mm-	
		SIZE	DRAWING NO.
		C	PSC-4277
		REV	03
DO NOT SCALE DRAWING		SHEET 2 OF 2	



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